

DISCOVER SMART TECHNOLOGIES

We are manufacturers of
Ansol Solder Wire, Sticks & Fluxes



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OUR COMPANY PROFILE

PREMIER INDUSTRIES was established in 1987 to manufacture exclusively Solder wire,sticks,Fluxes as per ISS,BSS,DIN,and ASTM standards. The Company has made remarkable progress during the period and become a leading Solder Wire & Fluxes manufacturer in India. and is the only unit among such manufacturers to use exclusively *Latest technology*. The company is managed by a team of well - qualified technical and skilled workforce to achieve the desired quality product.

OUR RESPONSIBILITY

It is Company Commitment to ensure Total quality of Your Soldering joint. And supply you more than just Solders & Fluxes.We supply a customised solution, with solder wire,sticks & Fluxes to your application, Which will produce soldered joints of an agreed quality.

QUALITY POLICY

- The company dedicates completely to the concept of customer satisfaction through Quality par excellence.
- In order to achieve total quality and in-depth knowledge the company ensures perfect training from top to bottom work force.
- The company cares for employees welfare & motivates to maintain quality and environment congenial for his total involvement.
- The Company has complete in house Latest testing facilities to check the quality of products.

QUALITY ACHIEVEMENTS

- The Company has produced a wide range of Solder wire, Sticks & Fluxes to adapt to your requirement.
- Their quality and reliability leads to:

- An Improved Quality\
- A Cost effective production process.
- An increased productivity
- Competitive Price



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ANSOL SOLDERING PASTE FLUX

- It is blend of water white rosin, surfactants and activators especially formulated for assembling printed circuits and other components. It can be applied to the areas to be soldered by any convenient method.

ANSOL ALUMINIUM SOLDERING FLUX

- It is entirely non-chloride organic flux. It aids wetting, thereby making all the alloys easier to solder. In some Instance even eliminate the need of pre solder cleaning.It remove the tough oxide film on the aluminium,shield the bare metal from contact with the air and oxidation,and promote base metal wetting and solder flow.

ANSOL WATER SOLUBLE FLUX

- It is a water soluble organic activated flux.It is especially adaptable for the foam fluxing,,however, it can also be applied by dipping or brushing. It is used where inorganic fluxes are not corrosive to use and rosin fluxes are too inactive for the application. It is essential that the flux residues be completely and adequately removed.

PRODUCTS

ANSOL SOLDER WIRE & STICKS

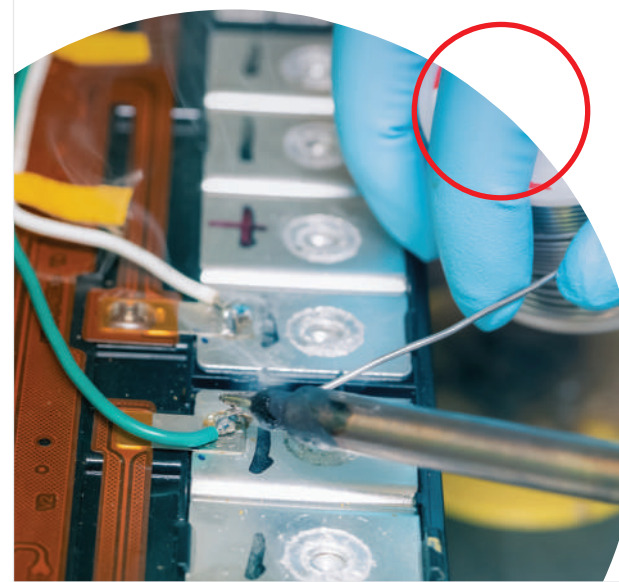
- To keep pace with rapid technological development in the electronic and electrical field **PREMIER INDUSTRIES** manufactured the **ANSOL** Rosin Core solder Wire and sticks with high grade pure and virgin materials, rigid Analytical quality control procedure being exercised on every cast. Highly skilled technicians and engineers specialized in the field properly checked the material to ensure the quality and reliability of the rosin core solder wire to meet world standard like **ISS, JIS, BSS, DIN, & ASTM**.

ROSIN ACTIVATED FLUXES

- It is a liquid solution containing water white rosin blended solvent system with activators. It is especially formulated for foam-fluxing,however,it can also be applied by dipping ,brushing or spraying.

LOW SOLIDS, NO CLEAN FLUXES

- It is halogen-free,low solids solvent system designed for wave soldering,conventional and surface mount circuit board assemblies. It can be applied by foaming ,spraying,dipping or brushing. The low solids content and the properties of activators system of the fluxes require no-cleaning after soldering.The non corrosive and non-conductive residue of the flux usually have high insulation resistance.



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LEAD FREE SOLDERS WIRE

COMPOSITION	MELTING POINT °C	TENSILE STRENGTH Mpa/min	RECOMMENDED APPLICATION
Sn95.5/Ag4.0/Cu0.5	217-218	37	Used in electronic, electrical and components
Sn96.5/Ag3.0/Cu0.5	217-219	37	Eutectic alloy . Suitable for all types of pcbs .Excellent soldering results in wave soldering and good SMT process
Sn99/Ag0.3/Cu0.7	225-227	25	Most common solder alloy suitable for soldering of multilayer , PTH and single sided pcbs. Used in wave, dip and HAL soldering applications
Sn99.2/Cu0.6/Ag0.1	217-228	32	Low silver contents
Sn99/Cu0.6/BI0.4	219-225	32	Low cost proprietary lead free alloy
Sn99.3/Cu0.7	227	28	General purpose lead free alloy for soldering of electrical / electronics components and pcbs
Sn99.0/Cu1.0	227	32	Best suitable for electricals and metal components
Sn95/Sb5	236-243	35.2	Special alloy for automobile industry

FEATURES OF ANSOL SOLDER WIRES

ANSOL manufactures all grades of rosin cored , No clean , Halogen free and solid solder wire for specific requirements of electronics , automobile , consumers durables , telecom and electric industry. It is available in any size, grade , composition and flux percentage as per customer requirements

FLUX TYPE	PRODUCT CODE	COMPOSITION	FLUX CONTENT%	SPREAD FACTOR%	DIAMETER IN mm
RA	SnPb	Sn 63/Pb 37	2 to 3	>90	0.50 to 3.0
	SnPb	Sn60/Pb40	2 to 3	>90	0.50 to 3.0
	SnPb	Sn62/Pb36/Ag2.0	2 to 3	>90	0.50 to 3.0
	SnPb	Sn 50/Pb 50	2 to 3	>90	0.50 to 3.0
	SnPb	Sn 40/Pb 60	2 to 3	>90	0.50 to 3.0
	SnPb	Sn30/Pb70	2 to 3	>90	0.50 to 3.0
	SnPb	Sn 25/Pb 75	2 to 3	>90	0.50 to 3.0
	SnPb	Sn 20/Pb 80	2 to 3	>90	0.50 to 3.0
	SnPbAg	Sn5/Pb93.5/Ag1.5	2 to 3	>90	0.50 to 3.0
	SnPb	Sn 63/Pb 37	2 to 3	>85	0.50 to 3.0
RMA	SnPb	Sn 60/Pb40	2 to 3	>85	0.50 to 3.0
	SnPbAg	Sn62/Pb36/Ag2.0	2 to 3	>85	0.50 to 3.0
	SnPb	Sn 55/Pb45	2 to 3	>85	0.50 to 3.0
	SnPb	Sn 50/Pb50	2 to 3	>85	0.50 to 3.0
	SnPb	Sn 40/Pb60	2 to 3	>85	0.50 to 3.0
	SnPb	Sn 30/Pb70	2 to 3	>85	0.50 to 3.0
	SnPb	Sn 25/Pb75	2 to 3	>85	0.50 to 3.0
	SnPb	Sn 20/ Pb 80			
	SnPbAg	Sn5/Pb93.5/Ag1.5	2 to 3	>85	0.50 to 3.0
	Sn/ Zn	Sn 70/ ZN 30	SOLID		1.0 to 3.0
HALOGEN FREE & NO CLEAN					
	SnPb	Sn63/Pb37	1.1 to 2.2	>80	0.50 to 3.0
	SnPb	Sn60/Pb40	1.1 to 2.2	>80	0.50 to 3.0
	SnPbAg	Sn62/Pb36/Ag2.0	1.1 to 2.2	>80	0.50 to 3.0
	SnPb	Sn 50/Pb50	1.2 to 2.2	>80	0.50 to 3.0
	SnPb	Sn 40/Pb 60	1.2 to 2.2	>80	0.50 to 3.0
	SnPb	Sn 25/Pb75	1.2 to 2.2	>80	0.50 to 3.0
	SnPb	Sn20/Pb80	1.2 to 2.2	>80	0.50 to 3.0
	SnPbAg	Sn5/Pb93.5/Ag1.5	1.2 to 2.2	>80	0.50 to 3.0



SOLDER WIRE SN63PB37

Brand	Ansol
Composition	Sn63Pb37
Type of flux	RA
Melting Point	183°C
Conduct heat (J/m*s*K)	50
Density (25°C)	8.4
Application	Sn63Pb37 leaded solder wire can be used in the electronics,copper plate, semiconductor ,Hard disk drive,Optics-electronic, LCD, IC, SMT, PCB ,Medical field and biotech industries



SOLDER WIRE SN60PB40

Brand	Ansol
Composition	Sn60Pb40
Type of flux	RA
Melting Point	186°C
Conduct heat (J/m*s*K)	50
Density (25°C)	8.4
Application	Sn60Pb40 leaded solder wire can be used in the electronics, copper plate, semiconductor, Hard disk drive, Optics electronic, LCD, I C, SMT, PCB, Medical field and biotech industries.



SOLDER WIRE SN50PB50

Brand	Ansol Champion standard
Composition	Sn50Pb50
Type of flux	RA
Melting Point	183 - 214°C
Application	solder wire is the most popular leaded option for general purpose . It's a versatile solder that can be used for Electrical, radio, and other industrial applications. Comprised of 50% tin and 50% lead, it's a user-friendly option due to its great solder flow and low melting point



SOLDER WIRE SN40PB60

Brand	Ansol Champion deluxe
Composition	Sn40Pb60
Type of flux	RA
Melting Point	183 - 238°C
Application	Low cost general purpose solder for electrical industry



SOLDER WIRE SN35PB65

Brand	Ansol Sigma
Composition	Sn35Pb65
Type of flux	RA
Melting Point	183 - 247°C
Application	Low cost general purpose solder for electrical industry

SOLDER WIRE SN30PB70

Brand	Ansol Tiger
Composition	Sn30Pb70
Type of flux	RA
Melting Point	183 - 255°C
Application	Solder wire can be used for soldering electrical components, soldering PCBs; welding of copper plate and copper tube, welding of stainless steel and other general purpose welding. Good electrical conductivity

SOLDER WIRE SN25PB75

Brand	Ansol Heena
Composition	Sn25Pb75
Type of flux	RA
Melting Point	183 - 266°C
Application	Sn25Pb75 tin lead solder wire and solder bar can be applied in the thermal fuse, power semiconductor, calculators, and other electrical products. This type of solder wire is ideal for the soldering of stainless steel, zinc alloy, aluminum lamp caps, and some others. It is also used in the fans, electric wires, and the automotive printed circuit boards within the automotive and electronics industries. Moreover, our product can be suited for the spot welding of PCB components.

SOLDER WIRE SN20PB80

Brand	Ansol Leader Commercial
Composition	Sn 20/Pb 80
Type of flux	RMA
Melting Point	183-276 °C
Application	Suitable for relatively low requirements of the circuit board, such as: hardware equipment, automotive water tank lighting bulbs, cable connectors and other products welding

SOLDER WIRE SN15PB85

Brand	Ansol Active
Composition	Sn15Pb
Type of flux	RA
Melting Point	183-288 °C
Application	Suitable for relatively low requirements of the circuit board, such as: hardware equipment, automotive water tank lighting bulbs, cable connectors and other products welding

SOLDER STICKS/BAR

The quality of Ansol solder sticks / bar is the best as compared to the other solder brands. Ansol solder bar is made with the extrusion and vacuum process which conforms to a uniform alloy composition resulting in consistent and reliable quality. This process eliminates the contamination of metallic oxides and virtually drives out all sulphides, nonmetallic inclusion and other possible contaminations. In other solder bars the oxides can build up on the surfaces of molten solder to a brownish black mass which is called dross. But because of the special metal treatment done during manufacturing process, the surface of ANSOL solder alloy remains glossy in appearance for a longer time which results in less dross formation during wave soldering at the customer end.

ANSOL manufactures many compositions of Lead Free Solder Sticks which are listed below with their properties and recommended application.

COMPOSITION	MELTING POINT °C	TENSILE STRENGTH Mpa/min	RECOMMENDED APPLICATION
Sn95.5/Ag4.0/Cu0.5	217-218	37	Used in electronic, electrical and components
Sn96.5/Ag3.0/Cu0.5	217-219	37	Eutectic alloy. Suitable for all types of pcbs. Excellent soldering results in wave soldering and good SMT process
Sn99/Ag0.3/Cu0.7	225-227	25	Most common solder alloy suitable for soldering of multilayer, PTH and single sided pcbs. Used in wave, dip and HAL soldering applications
Sn99.7/Ag0.3	225		Replenishment alloy of Sn99/Ag0.3/Cu0.7 to stabilize copper in solder bath
Sn99.2/Cu0.6/Ag0.1	217-228	32	Low silver contents
Sn99.3/Cu0.7	227	28	General purpose lead free alloy for soldering of electrical / electronics components and pcbs
Sn99.0/Cu1.0	227	32	Best suitable for electricals and metal components
Sn95/Sb5	236-243	35.2	Special alloy for automobile industry
Sn80/Zn20	200		For aluminum soldering applications

LEAD FREE SOLDER STICK/BAR- SN99.3CU0.7

Brand	Ansol							
Melting Point	227-260°C							
Application	Used in electronic and electrical components General purpose lead free alloy for soldering of electrical / electronics components and pcbs							
Chemical Composition								
Ave	<u>Sn</u> 99.1	<u>Pb</u> 0.0247	<u>Sb</u> 0.0075	<u>Cu</u> 0.723	<u>Ag</u> 0.0005	<u>Cd</u> 0.0078	<u>In</u> 0.0030	<u>Zn</u> 0.0012
Ave	<u>Bi</u> 0.0048	<u>As</u> < 0.0040	<u>Al</u> 0.0006	<u>Fe</u> 0.0565	<u>Ni</u> 0.0016	<u>Co</u> 0.0011	<u>Au</u> 0.0017	<u>Ga</u> 0.0003
Ave	<u>Hg</u> < 0.0020	<u>Se</u> 0.0004						

ANSOL HAVE A WIDE RANGE OF QUALITY SOLDER ALLOY AS LISTED BELOW :

COMPOSITION	MELTING POINT °C	TENSILE STRENGTH Mpa/min	RECOMMENDED APPLICATION
Sn63/ Pb37	183	49	Eutectic solder for electronics, electricals, mobile and auto industry
Sn60/Pb40	183-187	51	General purpose solder. Suitable for hand soldering and dip soldering application
Sn 55/Pb45	183 - 212	44	Low cost general purpose solder
Sn 50/Pb 50	183 - 212	42	Low cost general purpose solder
Sn40/Pb60	183-238	45	Low cost general purpose solder for electrical industry
Sn30/Pb70	183 - 255		Low cost general purpose solder for electrical industry
Sn20/Pb80	183-276		Low cost general purpose solder for electrical industry
Sn15/Pb85	183-288		Low cost general purpose solder for electrical industry





SOLDER STICK/BAR- SN63PB37

Brand	Ansol							
Melting Point	183°C							
Application	Eutectic solder for electronics , electricals, mobile and auto industry							
Chemical Composition								
Ave	Sn 62.91	Pb 37.04	Sb 0.0095	Cu 0.0023	Ag 0.0015	Cd 0.0078	In 0.0030	Zn 0.0012
Ave	Bi 0.0038	As < 0.0040	Al 0.0006	Fe 0.0565	Ni 0.0026	Co 0.0011	Au 0.0027	Ga 0.0003
Ave	Hg < 0.0020	Se 0.0004						



SOLDER STICK/BAR- SN60PB40

Brand	Ansol							
Melting Point	183-187℃							
Application	General purpose solder. Suitable for hand soldering and dip soldering application							
Chemical Composition								
Ave	Sn 60.02	Pb 39.91	Sb 0.0090	Cu 0.0020	Ag 0.0014	Cd 0.0078	In 0.0030	Zn 0.0012
Ave	Bi 0.0028	As < 0.0040	Al 0.0006	Fe 0.0565	Ni 0.0026	Co 0.0011	Au 0.0027	Ga 0.0003
Ave	Hg < 0.0020	Se 0.0004						

SOLDER PASTE PRODUCTS

Premier industries high quality solder paste are uniquely formulated for superior performance to satisfy variety of assembly requirement, exact requirement of SMT component assembly, hybrid and chip bumping application, Premier Industries has developed solder paste for Indian electronic industries. Solder Paste is a homogenous mixture of finely graded oxide free pre-alloyed solder powder suspended on a thixotropic flux. Extremely rapid flow and increased wetting are obtained on Ansol solder paste. RMA paste is a solder paste that consists of RMA type flux satisfying with very mild halide. Flux residue after soldering becomes highly reliable coating with excellent insulation resistance.

NO CLEAN TYPE SOLDER PASTE

- No-clean solder paste is by far the most prevalent solder paste in modern electronic manufacturing, but there is still a purpose and a fit for water-soluble and RMA solder paste as well
- Designed for fine pitch application and ensures continual printing. It is highly reliable and requires no cleaning:
 - Exhibits excellent wettability.
 - Ensures minimal slumping and prevents solder balling and bridging.
 - Low colour flux residue offers superior cosmetic appearance.



SPECIFICATION

Metal : Tin & lead

Alloy : Sn63Pb37 , Sn60Pb40, Sn55Pb45

Brand : Ansol

DETAILS & FEATURES

- Different jar size : 500g
- Excellent Quality
 - Good Viscosity
 - Good fluidity
 - 6 months shelf life when refrigerated
- Good printing effect
 - Easy to printing
 - Good wetting property
 - Good slump resistance after printing
- Good solder ability
 - Round & nice solder bead
 - Bright solder joints
 - No clean flux



SOLDERING PASTE(FLUX)

Super flow soldering paste flux is ideal for soldering wide electric and electronic components & bonding will be free from faulty soldering problems. The flux has stable performance, volatile, long life cycle, the amount of Provincial, non-toxic, odourless, safe to use and reliable.

FEATURES AND SPECIFICATIONS:-

Brand : Ansol

Weight : 500g

Increases the flow of molten solder.



HEAT-SINK COMPOUND

Thermal conductive grease (1TC,2TC,3TC)

ANSOL thermal grease is a kind of heat conducting & insulating silicone grease. Thermal grease also named thermal paste or heat sink compound. This product has good thermal conductivity and dielectric properties, weather resistance, anti-ultraviolet property and excellent moisture-proof insulation property.

PRODUCT APPLICATION

- It is widely used in various electronic products, and the contact surface between the heating element and the heat radiating device in the electrical equipment
- It is used in the contact surface between the radiator of the LED lamp and the PCB. Suitable for SMD high-power lamp

FEATURES/ BENEFITS

- Good thermal conductivity
- Low oil bleed
- Good electrical insulation and stability with low viscosity
- Compliance with the ROHS directive requirements.
- Stable at -60°C to +200°C
- No cure and no flow
- Achieve thin bond lines under low pressure



ROSIN BASED LIQUID SOLDERING FLUX

- It is widely used in various electronic products, and the contact surface between the heating element and the heat radiating device in the electrical equipment
- It is used in the contact surface between the radiator of the LED lamp and the PCB. Suitable for SMD high-power lamp

APPLICATION:

- Rosin Based Soldering Flux applicable in any of the existing wave soldering machines used in the industry today. Application of the flux can be any of the three methods
- Dip, Wave, and Foam. Preheat temperature of between 950C and 1100 C on the component side of the board is recommended
- For best foaming result, the level of flux in the fluxing tank should be maintained at about 1.3 to 2.0 cm above the foaming stone
- Periodic monitoring of specific gravity with a hydrometer or automatic density censoring systems and addition of the appropriate amount of flux thinner is necessary to ascertain consistent soldering results.

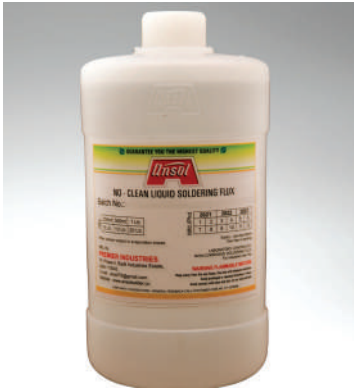
TECHNICAL PROPERTY

PROPERTY	UNIT	RESULT
Appearance		White Paste1
Specific Gravity	g/ml	1.8 - 2.2
Volatile Matter %	200°C /8H	≤ 1.0
Coefficient of thermal conductivity	W/mk	1.0
Voltage breakdown strength	kv/mm	>5
Limit Temperature	°C	~50~250

MERITS OF USING RMA FLUX:

- Low halide
- Low residue
- Very easy to use
- No icicles and bridges formations
- Very stable foaming characteristics
- Safe residue
- High S.I.R. value
- Good shining quality finishing to the solder fillets

NO CLEAN LIQUID SOLDERING FLUX



Physical State	Liquid
Material Type	Colorless liquid
Usage/Application	Industrial
Country of Origin	Made in India

PRODUCT DESCRIPTION

As the first among the best, we present the clients with the superior quality of No Clean Flux. Free from halogen, the offered no clean flux is used for the purpose of wave soldering for both conventional through hole. As a quality focused name, the premium grade of no clean flux is never compromised and is maintained in accordance to the international set standards.

SOLDERING FLUXES:

Flux is indispensable in the soldering of electronic components and other applications. A soldering flux performs many functions, the most important of which is the removal of oxides film, other tarnished film and surface film from the metal to be soldered. It exposes clean surfaces for optimum wetting and solder 'bond' formation. A flux's ability to prepare good surface for soldering is the measure of its activity. From our long and vast experience, we have constantly researched flux technology and have developed various types of fluxes, which provide unrivaled performances.

RANGE OF FLUXES DEVELOPED BY ANSOL:

NON ACTIVATED FLUX:

This flux is a mixture of high-quality WW rosin and alcohol, having solid content between 30-40%. The excellent mobility of the flux is caused by the low surface tension. It is used where flux residue removal is not necessary or where the circuit is affected by low level current leakage. It is mainly used for wire and component lead tinning. Residue is non corrosive and meets all the requirements of MIL-standard.

RMA (ROSIN MILDLY ACTIVATED) FLUXES :

ANSOL has developed special mildly active fluxes for electronic and electrical industries whereslightly active fluxes are required for foam fluxing as well as for dipping and brushing methods. The formulation of this flux has beenadjusted in such a manner thateven a low air pressure will produce a uniform head of foam bubbles. This flux is available in different compositions(solid contents etc) .

RA TYPE (ROSIN ACTIVATED) FLUX

Formulated for high speed and special soldering requirements of electrical components. This flux can be applied by dipping, foaming and spraying. The flux residue is too dry, non-sticky and non-corrosive but may require post solder cleaning in circumstances .The residue can easily be removed by using solvents.

NO CLEAN FLUX:

- Halogen free
- Non-corrosive and tack-free residue
- Reduced odour associated with soldering process
- Very easy to use
- Very economical
- Eliminate the need and expense of cleaning
- Very stable foaming characteristics
- Safe residue
- Excellent soldering finish can be obtained with no occurrence of solder balling, bridge formation, icicles etc
- Board probing after soldering can be easily done without cleaning
- No switch contact problems
- No blockage to spray nozzle

FEATURES:

- Non-corrosive and tack-free residue
- Reduced Odor associated with soldering process
- Very easy to use

LOW SOLID NO CLEAN FLUXES:

The low solid fluxes areorganic based, having very low solid contents formulated for wave soldering of multilayer, single and double-sidedbare copper lacquer / OSP coated , solder plated printed circuit boards. These fluxes contain a small percentage of unique rosin , proprietary activators and a special solvent system which leaves very thin , uniform and tack free transparent residues after soldering. Assemblies soldered with these fluxes have greater surface insulation resistance ,thermal stability and provides excellent performance in pin testing. The residues are non corrosive ,non conductive and non hygroscopic, hence no post solder cleaning is required. These fluxes are available in halogen free version also. Key features of our fluxes are : fast wetting , bridge free strong and reliable solder joints, no solder balls , better thermal stability and greater surface insulation resistance. Our fluxes are widely being used inconsumer , automobile , electrical , telecom and lighting industries .

ROSIN FREE NO CLEAN / HALOGEN FREE FLUXES: These fluxes are rosin free having 1.5 to 2.5 % solid contents and are totally halide free. Due to the absence of halide and careful incorporation oforganic activator system, these fluxes are safe. The small residuesis nonconductive , non corrosive and non hygroscopic thus, no post solder cleaning is required. It passes all the tests prescribes as per IPC standards IPC TM 650 . The residue on comb pattern board was tested to possess excellent surface insulation resistance and the SIR values observedhigher than 10magaohm /cm set by international standards. These fluxes are both effectively and popularly used in the consumer tele communication and computer industries. These fluxes are suitable for both bare copper and solder plated circuit boards.

WATER SOLUBLE FLUXES (ANSOL)

This flux is formulated from organic compound dissolved in a suitable solvent of highest purity. Post soldering residue is water soluble and can be cleaned by using water. These highly effective fluxes are employed for various electronic soldering applications.

KEY FEATURES:

- Neutral flux with pH- 6-8
- Excellent fluxing action
- Shiny and bright solder joints
- Does not attack soldering or cleaning equipment.

ANSOL FLUX SELECTION GUIDE

S.NO.	TYPE OF FLUX	COLOR	SPECIFIC GRAVITY AT 20°C	SOLID CONTENTS WT (%)	RECOMMENDED APPLICATION
1.	302 SOLDERING FLUX	COLOURLESS	0.795-0.800	1.5 TO 2.5	• Halide & rosin free no clean flux with almost zero residues • Suitable for both bare copper & solder plated circuit boards • Most suitable for computer mother board, telecom & other very sophisticated micro circuits soldering application
2.	NO CLEAN SOLDERING FLUX	LIGHT YELLOW	0.794-0.805	4-5	• Very low transparent residue • deal for telephone, telecom, lighting& consumers PCB • Good contact for checker pins
3.	RMA SOLDERING FLUX	PALE YELLOW	0.82±0. 005	13-17	• Suitable for high density boards This flux has high reliability and soldering for consumer products
4.	01 LIQUID SOLDERING FLUX	COLOURLESS	0.795-0.7980	2.5-3.5	• Flux is indispensable in the soldering of electronic components and other applications. A soldering flux performs many functions, the most important of which is the removal of oxides film, other tarnished film and surface film from the metal to be soldered. It exposes clean surfaces for optimum wetting and solder 'ANSOL' formation. A flux ability to prepare good surface for soldering is the measure of its activity.



ALUMINUM SOLDERING FLUX

Aluminum Soldering Flux Widely used in soldering process to make it easy, the offered flux ensures shiny joints. This flux is processed with the use of supreme quality basic ingredients under suitable conditions. Especially used in aluminium as well as aluminium soldering applications at low temperature, this flux resists melting of metal surface in an effective manner. We provide this Aluminum Soldering Flux

KEY POINTS:

- Resists to electrolytic action
- Prevents from leakage
- Requires low temperature

ALUMINIUM TO ALUMINIUM , ALUMINIUM TO COPPER SOLDERING FLUX

This flux paste is designed for aluminum-to-aluminum or aluminum-to-copper soldering at low temperatures.

- Low-temperature soldering prevents aluminum components from melting.
- Resists electrolytic action between aluminum and copper, preventing leakage between dissimilar metals